

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MICHEL KOOPMANS	03/26/2014
SHIJIAN LUO	03/21/2014
DAVID R. HEMBREE	03/20/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 S. FEDERAL WAY, P.O. BOX 6
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707-0006
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14231101
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(206)359-4209
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	206-359-8000
<b>Email:</b>	swhelan@perkinscoie.com
<b>Correspondent Name:</b>	PERKINS COIE LLP - MICRON PATENT-SEA
<b>Address Line 1:</b>	PO BOX 1247
<b>Address Line 4:</b>	SEATTLE, WASHINGTON 98111-1247
<b>ATTORNEY DOCKET NUMBER:</b>	10829-9112.US00
<b>NAME OF SUBMITTER:</b>	STEPHEN P. WHELAN
<b>SIGNATURE:</b>	/Stephen P. Whelan/
<b>DATE SIGNED:</b>	03/31/2014
<b>Total Attachments: 5</b> source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif	

PATENT

## ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Michel Koopmans, having a mailing address of 2571 S. Waterbury Lane, Boise Idaho 83706;
- Shijian Luo, having a mailing address of 13358 W Tapatio Drive, Boise, Idaho 83713; and
- David R. Hembree, having a mailing address of 11074 W. Edgehill Drive, Boise, Idaho 83709.


The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH IMPROVED THERMAL PERFORMANCE AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 (the "Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all

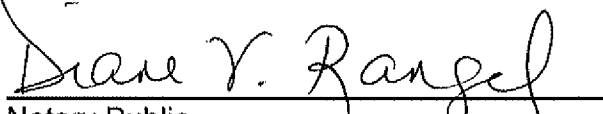
Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deem necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

Date: 3/26/2014

Signature   
Michel Koopmans

United States of America )  
State of Idaho ) ss.  
County of Ada )

On this 26<sup>th</sup> day of March, 2014 before me  
personally came Michel Koopmans, to me known to be the individual  
described in and who executed the foregoing instrument, and acknowledged execution  
of the same.

  
Notary Public



Date: 03/21/2014 Signature Shijian Luo  
Shijian Luo

United States of America )  
State of Idaho ) ss.  
County of Ada )

On this 21st day of march, 2014 before me  
personally came Shijian Luo, to me known to be the individual  
described in and who executed the foregoing instrument, and acknowledged execution  
of the same.

Diane V. Rangel  
Notary Public



Date: 3/20/14 Signature David R. Hembree  
David R. Hembree

United States of America )  
State of Idaho ) ss.  
County of Ada )

On this 20<sup>th</sup> day of March, 2014 before me  
personally came David R. Hembree, to me known to be the individual  
described in and who executed the foregoing instrument, and acknowledged execution  
of the same.

Diane V. Rangel  
Notary Public

